Appl. No. 10/775,748

Amdt. dated February 15, 2006

Reply to Office action of November 15, 2005

AMENDMENTS TO THE CLAIMS

The listing of claims replaces all prior versions, and listings, of claims in the

application:

<u>Listing of Claims</u>

1-11. (Cancelled)

12. (Currently amended) An arrangement for contacting terminals of a substrate

comprising a substrate surface, a first terminal having a first terminal surface, and a

second terminal having a second terminal surface, the first terminal surface being located

at a shorter distance from the substrate surface than the second terminal surface, the

arrangement comprising:

a first insulating layer on the substrate surface, having an insulation-layer surface

being located at a longer distance from the substrate surface than the second terminal

surface, wherein a part of said first insulating layer is arranged between the first and the

second terminal;

a second insulating layer arranged on the first insulating layer;

wherein the first insulating layer has a contact via which extends from the

insulation-layer surface to the first terminal surface and is filled with a first conductive

material, and wherein the second insulating layer has a recess, said recess penetrating the

second insulating layer and former, extending [[up]] to the first conductive material and

into the first dielectric layer [[7]] and being filled with a second conductive material, such

that the second conductive material contacts the first conductive material on a top surface

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and on a portion of a side surface thereof; and

wherein a recess extends to the second terminal surface through the first and

second insulating layers, and is filled with a third conductive material.

13. (Previously presented) The arrangement as claimed in claim 12, wherein the first

terminal is one of a base terminal and a collector terminal, and the second terminal is an

emitter terminal, arranged on a stack, of a bipolar transistor.

14. (Previously presented) The arrangement as claimed in claim 12, wherein the first

terminal is one of a source terminal and a drain terminal, and the second terminal is a gate

terminal of a field-effect transistor.

15. (Previously presented) The arrangement as claimed in claim 12, wherein the first

terminal is formed on the substrate and is selected from the group of a base terminal of a

bipolar transistor, a collector terminal of a bipolar transistor, a gate terminal of a field-

effect transistor, a source terminal of a field-effect transistor and a drain terminal of a

field-effect transistor.

16. (Previously presented) The arrangement as claimed in claim 12, wherein at least

one of the first conductive material, the second conductive material and the third

conductive material comprises metal.

17. (Original) The arrangement as claimed in claim 12, wherein the first conductive

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material is tungsten.

18. (Previously presented) The arrangement as claimed in claim 12, wherein at least

one of the second and third conductive materials is copper.

19. (Original) The arrangement as claimed in claim 12, wherein the second

conductive material is conductively connected to the first conductive material and forms

a first contact terminal, and wherein the third conductive material is conductively

connected to the second terminal and forms a second contact terminal.

20. (Original) The arrangement as claimed in claim 12, wherein the first and second

contact terminals form a wiring plane.